



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC014N06NS	Issued	16. June 2021
MA#	MA005426648		
Package	PG-TDSON-8-26	Weight*	116.34 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.818	1.56	1.56	15630	15630
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		126	
	non noble metal	iron	7439-89-6	0.049	0.04		420	
	non noble metal	copper	7440-50-8	48.769	41.93	41.98	419192	419738
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	385	385
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		701	
	plastics	epoxy resin	-	6.447	5.54		55414	
	inorganic material	silicondioxide	60676-86-0	34.275	29.46	35.07	294608	350723
leadfinish	non noble metal	tin	7440-31-5	1.392	1.20	1.20	11961	11961
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1666	1666
solder	non noble metal	tin	7440-31-5	0.050	0.04		428	
	noble metal	silver	7440-22-4	0.062	0.05		535	
	non noble metal	lead	7439-92-1	2.380	2.05	2.14	20455	21418
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			44	
	non noble metal	iron	7439-89-6	0.017	0.01		147	
	noble metal	silver	7440-22-4	0.635	0.55		5462	
	non noble metal	copper	7440-50-8	17.131	14.73	15.29	147252	152905
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			26	
	non noble metal	copper	7440-50-8	2.971	2.55	2.55	25540	25574
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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